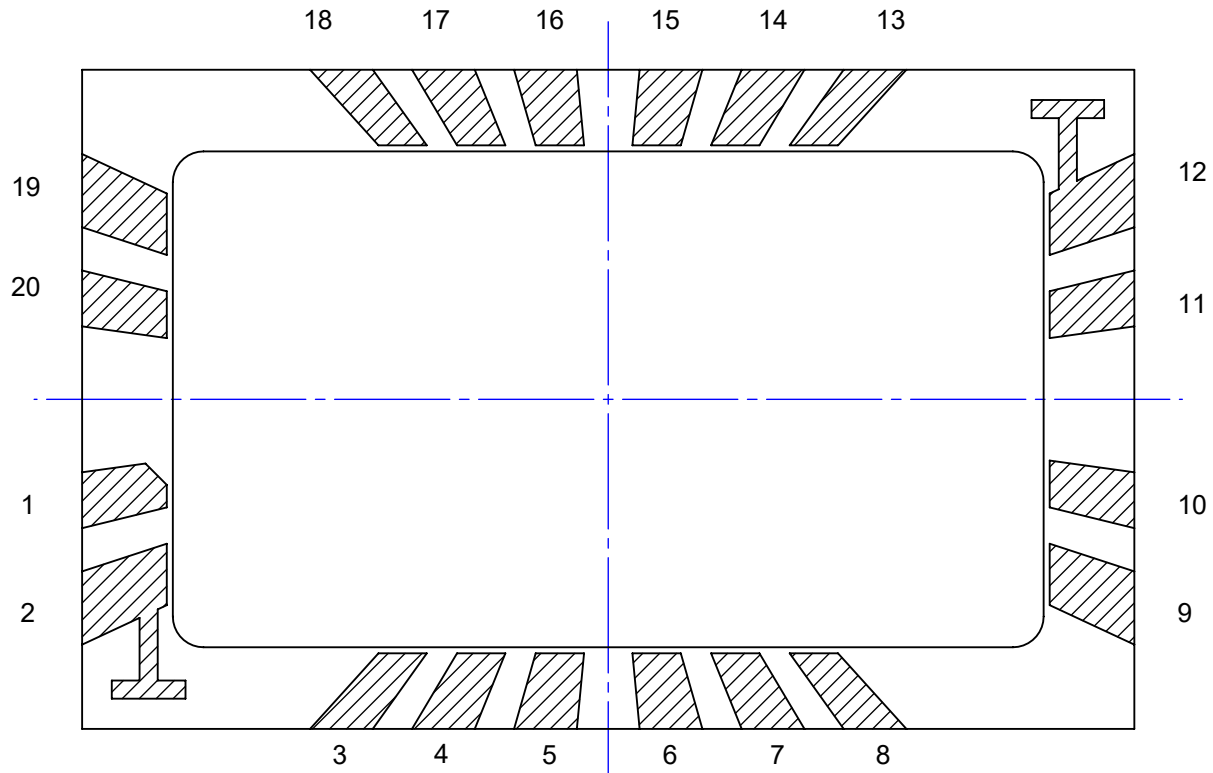


Notes: (Unless Otherwise Specified).

1. DIMENSIONS IN MM.
2. ALL EXPOSED METAL AND METALLIZED AREA SHALL BE GOLD PLATED.
3. 60 MICRO INCH MIN. THK. OVER NICKEL PLATED.
4. SEAL AREA AND DIE ATTACH AREA SHALL BE ISOLATED FROM ANY LEADS. (ZERO GROUND)

APPROVALS	DATE	TopLine®			
DRAWN T. Au	2/9/2022				
ENG M. Hart	2/9/2022	TITLE CSOP20G-N161x283 OPEN CERAMIC PACKAGE			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		6:1	A	162002	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 5
REVISED					

BONDING PADS



TopLine[®]

TITLE CSOP20G-N161x283
OPEN CERAMIC PACKAGE

SCALE 16:1	SIZE A	DRAWING NO. 162002	REV A
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DO NOT SCALE DRAWING

SHEET 2 OF 5

**DIMENSION
CAVITY AND SEAL RING**

DESCRIPTION	REF.	DIMENSION INCH	DIMENSION MM
DIE CAVITY	DIE	0.161 x 0.283	4.09 x 7.19
BOND O.D.	BOND	0.215 x 0.343	5.45 x 8.70
SEAL RING I.D.	SR I.D.	0.215 x 0.343	5.45 x 8.70
SEAL RING O.D.	SR O.D.	0.285 x 0.413	7.24 x 10.50

TopLine®

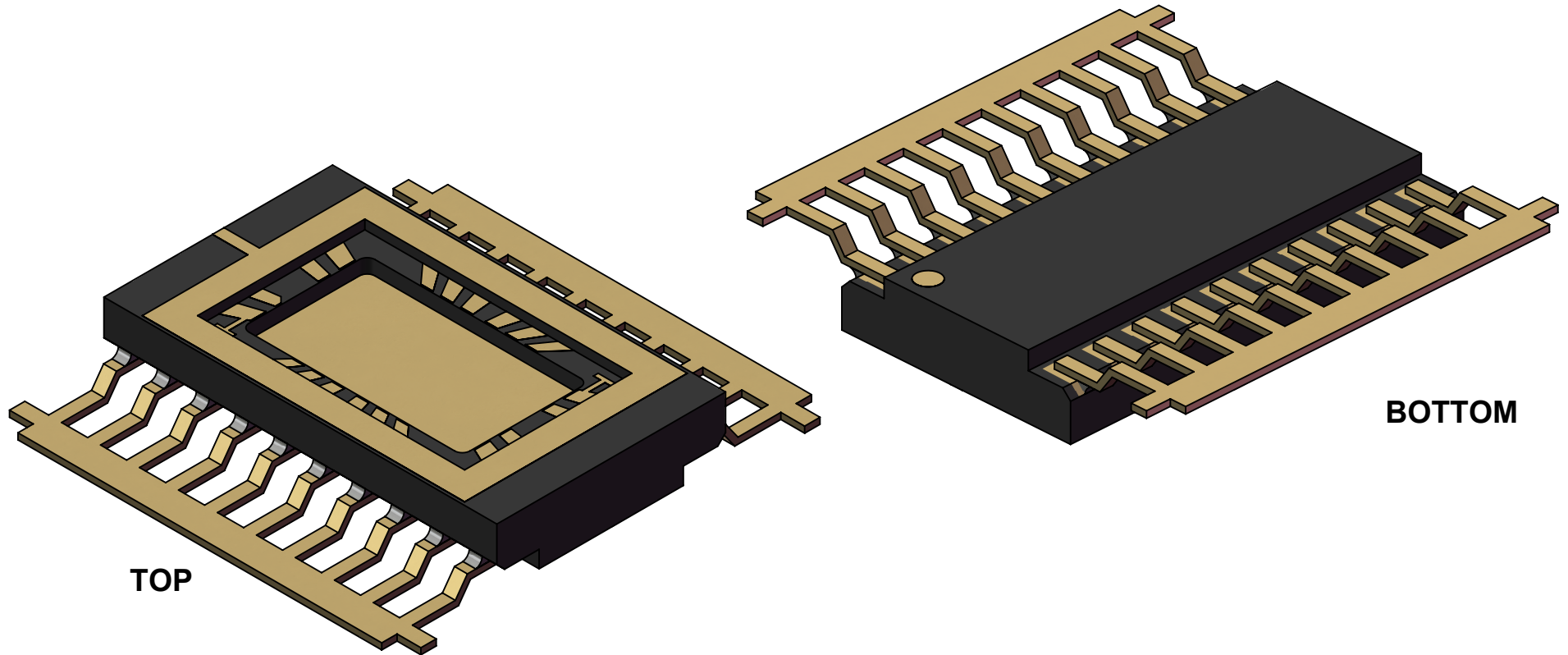
TITLE CSOP20G-N161x283
OPEN CERAMIC PACKAGE

SCALE NONE	SIZE A	DRAWING NO. 162002	REV A
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DO NOT SCALE DRAWING

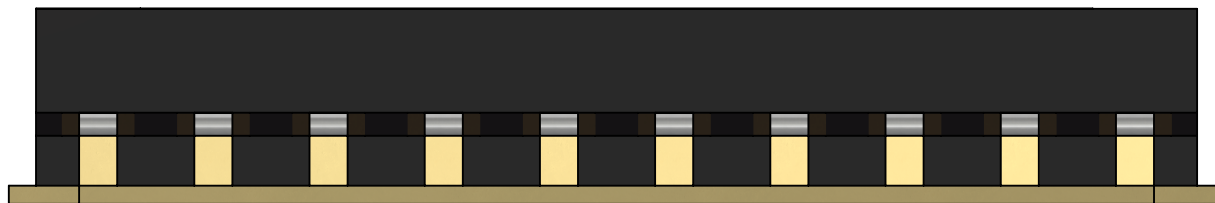
SHEET 3 OF 5

**MODELS
OPEN CAVITY**



TOP

BOTTOM



EDGE

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TITLE CSOP20G-N161x283
OPEN CERAMIC PACKAGE

SCALE 7:1	SIZE A	DRAWING NO. 162002	REV A
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DO NOT SCALE DRAWING

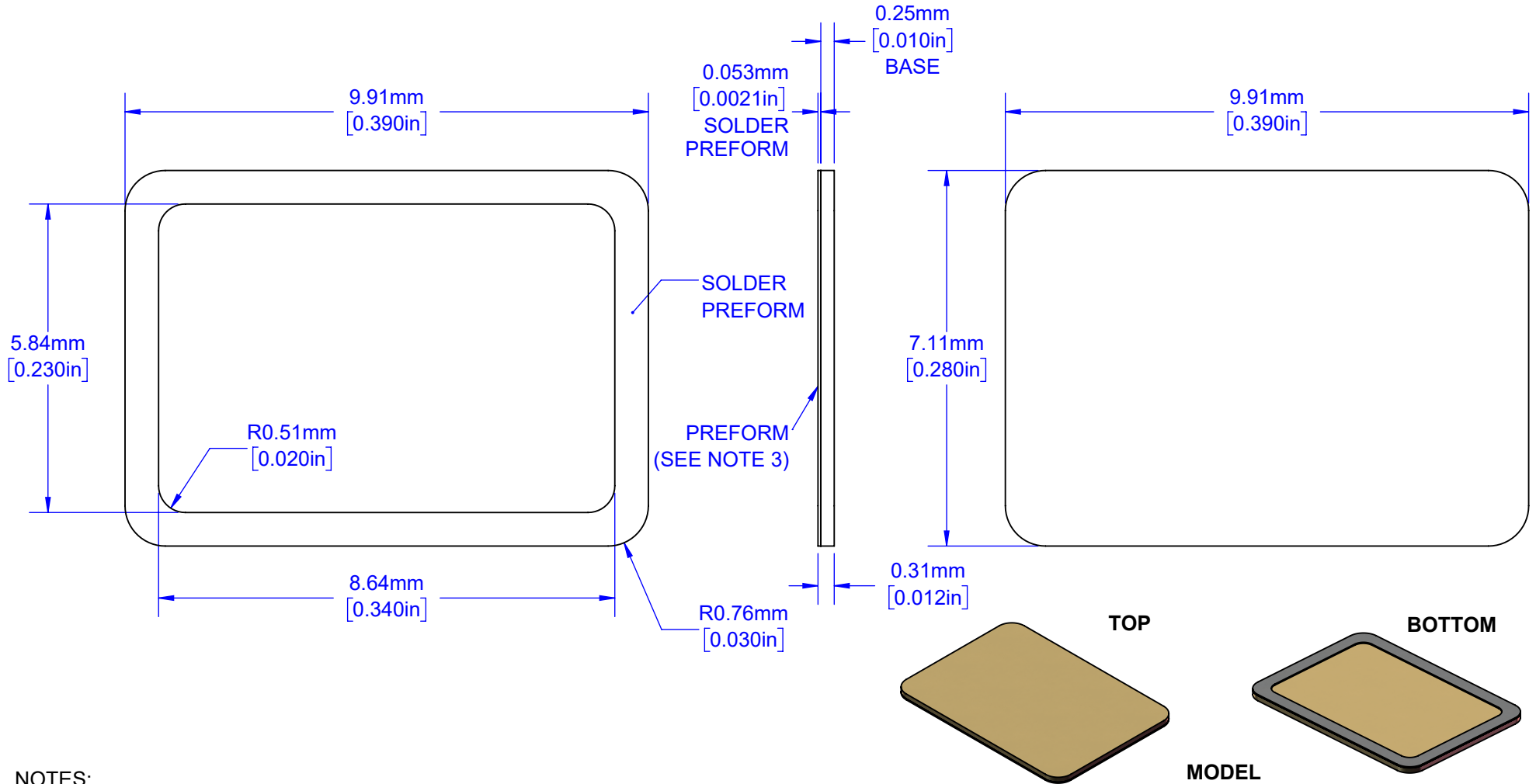
SHEET 4 OF 5

COMBO LID

BOTTOM

SIDE

TOP



NOTES:

1. BASE MATERIAL: KOVAR or ALLOY 42.
2. PLATING: Ni 50~350 MICRO-INCH PER SIDE.
Au 25 MICRO-INCH MIN PER SIDE.
3. SOLDER PREFORM: Au 80% ±1.0 Sn 20%.
4. FLATNESS 1.0MIL (25µm) MAXIMUM PER 0.5-inch (12.7mm).

REF: HR-C-243

TopLine®			
TITLE		CL-390x280-A COMBO LID	
SCALE	SIZE	DRAWING NO.	REV
9:1	A	131280	A
DO NOT SCALE DRAWING			SHEET 5 OF 5